



100% Material Declaration Data Sheet HQ304

PK213 (v1.0) October 18, 2006

Material Declaration Data Sheet

Average Weight: 28.511 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.15449	0.58%
	Silicon	7440-21-3	100.00		0.15449	
Die Attach Material					0.01427	0.05%
	Silver	7440-22-4	75.00		0.010699	
	Epoxy (EP)	Trade Secret	25.00		0.003566	
Mold Compound					7.45805	28.13%
	Epoxy Resin (EP)	Trade Secret	15.00		1.118708	
	Silica	60676-86-0	85.00		6.339344	
Leadframe					0.90153	3.40%
	Copper	7440-50-8	96.20		0.867270	
	Nickel		3.00		0.027046	
	Silicon		0.65		0.005860	
	Magnesium		0.15		0.001352	
Leadframe Plating					0.00155	0.01%
	Silver	7440-22-4	100.00		0.00155	
Heat Slug					17.87660	67.43%
	Copper	7429-50-8	100.00		17.87660	
Ext. Heat Sink plating					0.01157	0.04%
	Nickel	7440-02-0	100.00		0.01157	
Bond Wire					0.01231	0.05%
	Gold	7440-57-5	100.00		0.01231	
Ext. Plating					0.05572	0.21%
	Tin	7440-31-5	85.00		0.047361	
	Lead	7439-92-1	15.00		0.008358	

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
10/18/06	1.0	Initial release.